

## **General Description**

The WSD2012DN25 is the highest performance trench N-ch MOSFETs with extreme high cell density, which provide excellent RDSON and gate charge for most of the small power switching and load switch applications.

The WSD2012DN25 meet the RoHS and Green Product requirement with full function reliability approved.

### **Features**

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent Cdv/dt effect decline
- Green Device Available

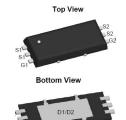
## **Product Summery**

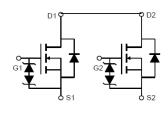
BVDSS	RDSON	ID
20V	$9.5 m\Omega_{(max)}$	11A

## **Applications**

- Power management in portable and battery operated products
- DC-DC Power System
- ESD:2KV

## **DFN2X5 Pin Configuration**





## **Absolute Maximum Ratings**

Symbol	Parameter	Rating	Units
$V_{DS}$	Drain-Source Voltage	20	V
$V_{GS}$	Gate-Source Voltage	±12	V
I <sub>D</sub> @T <sub>A</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	11	Α
I <sub>D</sub> @T <sub>A</sub> =70°C	Continuous Drain Current, V <sub>GS</sub> @ 4.5V <sup>1</sup>	9	Α
I <sub>DM</sub>	Pulsed Drain Current <sup>2</sup>	95	А
P <sub>D</sub> @T <sub>A</sub> =25℃	Total Power Dissipation <sup>3</sup>	1.7	W
P <sub>D</sub> @T <sub>A</sub> =70℃	Total Power Dissipation <sup>3</sup>	1.0	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	-55 to 150	$^{\circ}$

### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup> (Steady State)		75	°C/W
R <sub>θJA</sub>	Thermal Resistance Junction-ambient <sup>1</sup> (t<10S)		40	°C/W



## Electrical Characteristics (T<sub>J</sub>=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	20			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃ , I <sub>D</sub> =1mA		0.022		V/℃
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =5.5A	5.0	7.0	9.5	mΩ
		V <sub>GS</sub> =2.5V , I <sub>D</sub> =5.5A	6.8	9.0	13	
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	0.3	0.65	1.0	V
$\triangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient			-2.32		mV/℃
	Dunin Course Legland Current	V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =25℃			1	
I <sub>DSS</sub>	Drain-Source Leakage Current  V <sub>DS</sub> =16V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5	uA	
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm$ 12 $V$ , $V_{DS}$ =0 $V$			±100	nA
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =10A		65		S
$R_g$	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		2500		Ω
Qg	Total Gate Charge (4.5V)	V <sub>DS</sub> =10V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =5.5A	10	12.5	15	
Q <sub>gs</sub>	Gate-Source Charge			5.5		nC
Q <sub>gd</sub>	Gate-Drain Charge			6.5		
T <sub>d(on)</sub>	Turn-On Delay Time	$V_{DD}$ =10V , $V_{GS}$ =10V , $R_{G}$ =1 $\Omega$ , $I_{D}$ =1A , $RL$ =10 $\Omega$		1.1		
Tr	Rise Time			2.6		- μs
T <sub>d(off)</sub>	Turn-Off Delay Time			7		
T <sub>f</sub>	Fall Time			7.4		
C <sub>iss</sub>	Input Capacitance	V <sub>DS</sub> =10V , V <sub>GS</sub> =0V , f=1MHz	1000	1256	1511	
Coss	Output Capacitance		150	220	295	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		100	168	238	

## **Diode Characteristics**

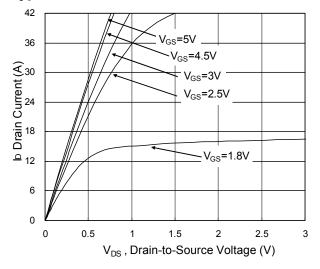
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,4</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			3	Α
I <sub>SM</sub>	Pulsed Source Current <sup>2,4</sup>				45	Α
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25℃		0.58	1.0	V
t <sub>rr</sub>	Reverse Recovery Time	IF=10A,dI/dt=500A/µs , Tյ=25℃		11		nS
Q <sub>rr</sub>	Reverse Recovery Charge			15		nC

#### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, t<10sec.
- 2.The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2%
- 3.The power dissipation is limited by 150 ℃ junction temperature
- $\textbf{4.The data is theoretically the same as } \textbf{I}_{D} \text{ and } \textbf{I}_{DM} \text{ , in real applications , should be limited by total power dissipation.}$



## **Typical Characteristics**



**Fig.1 Typical Output Characteristics** 

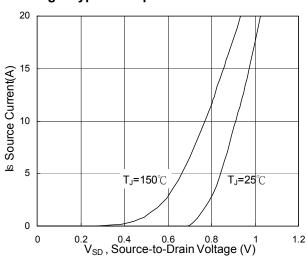


Fig.3 Forward Characteristics Of Reverse

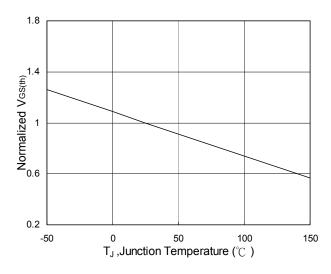


Fig.5 V<sub>GS(th)</sub> vs. T<sub>J</sub>

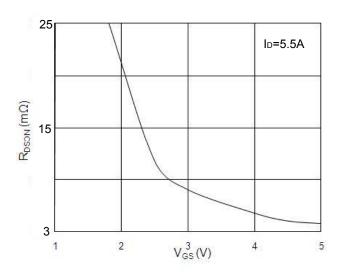


Fig.2 On-Resistance vs. Gate-Source

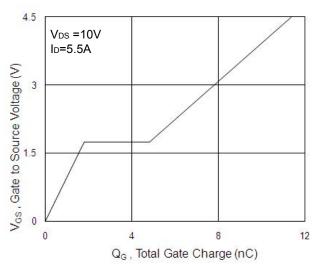


Fig.4 Gate-Charge Characteristics

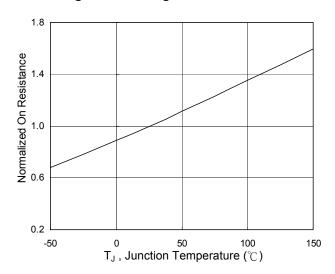
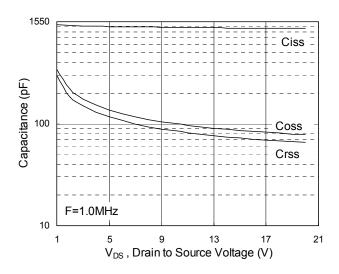


Fig.6 Normalized R<sub>DSON</sub> vs. T<sub>J</sub>





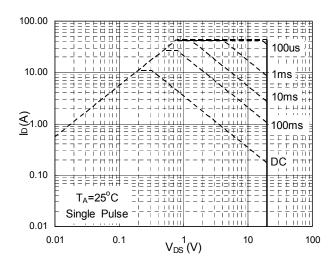


Fig.7 Capacitance

Fig.8 Safe Operating Area

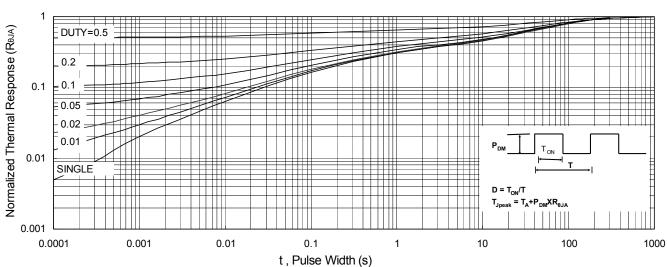


Fig.9 Normalized Maximum Transient Thermal Impedance

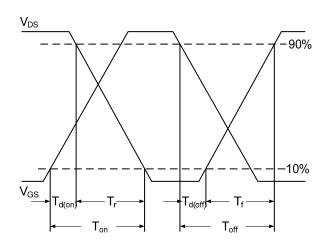


Fig.10 Switching Time Waveform

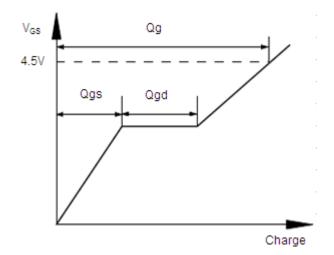


Fig.11 Gate Charge Waveform



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